

09823431 040901

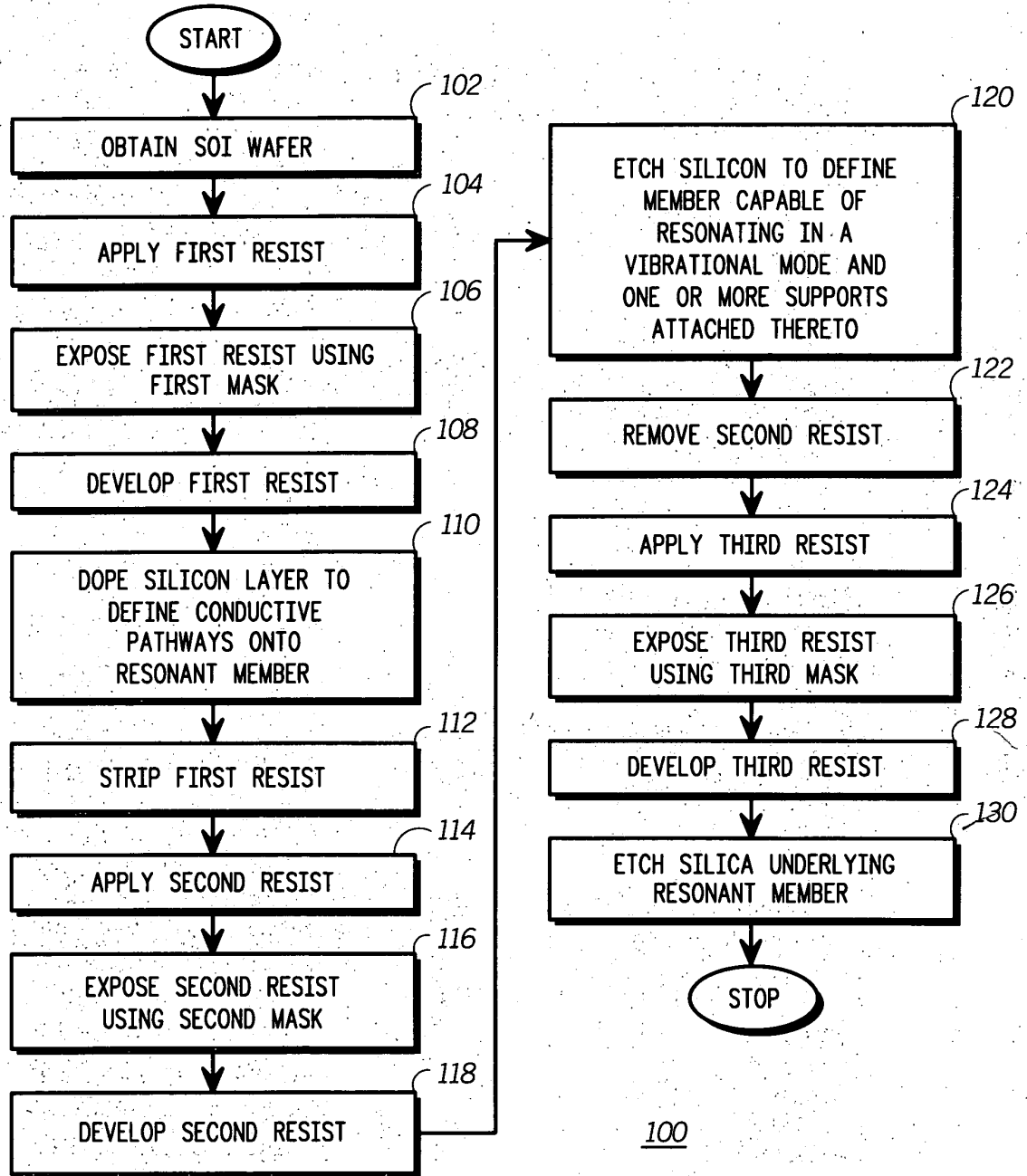


FIG. 1

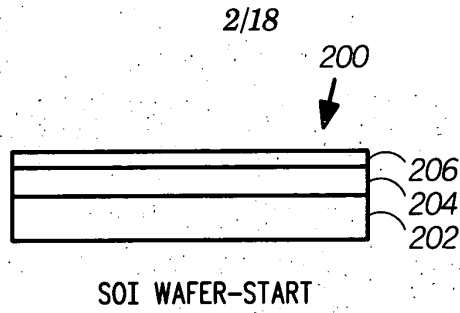


FIG. 2

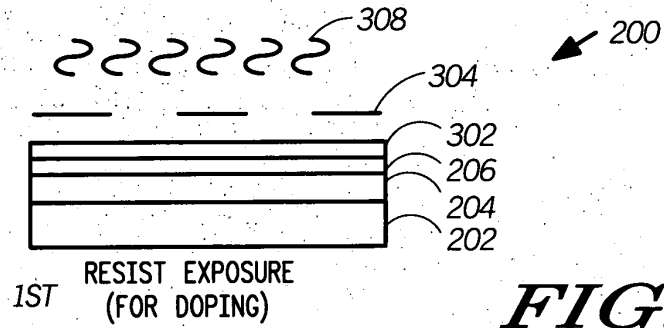


FIG. 3

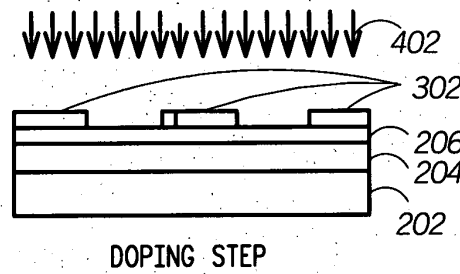


FIG. 4

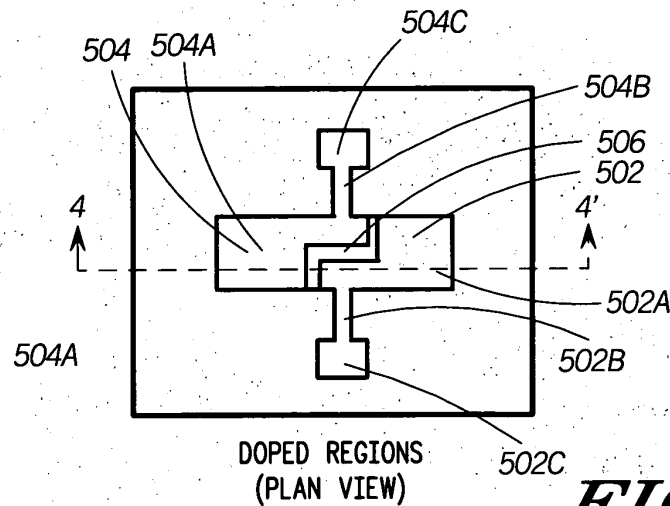
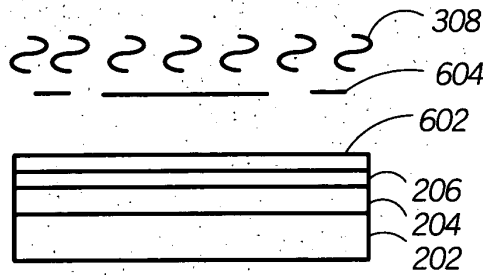


FIG. 5

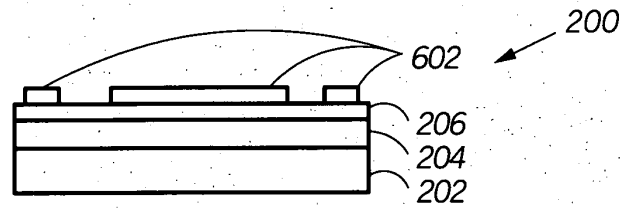
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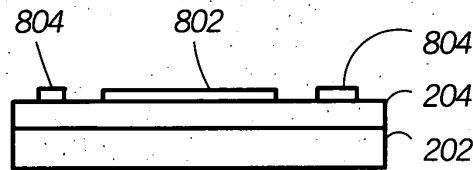
2ND RESIST EXPOSURE
(FOR SILICON ETCH)

FIG. 6



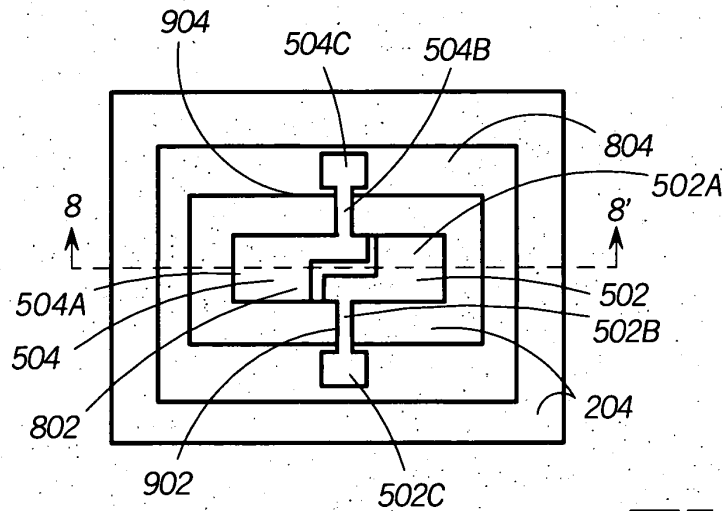
DEVELOPED RESIST

FIG. 7



ETCHED SILICON LAYER
SECTIONAL ELEVATION

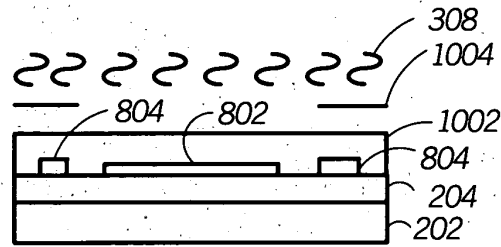
FIG. 8



ETCHED SILICON-PLAN VIEW

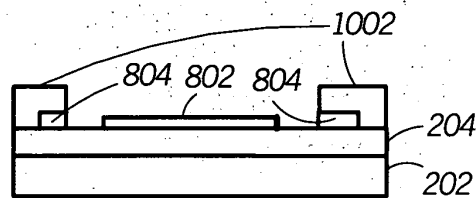
FIG. 9

FIG. 9



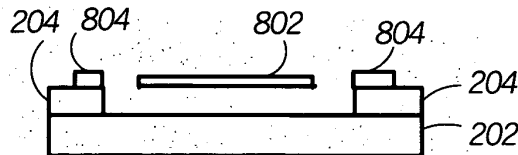
3RD RESIST EXPOSURE
(FOR SI02 ETCH)

FIG. 10



DEVELOPED RESIST

FIG. 11



AFTER SI02 ETCH

FIG. 12

FOOTPRINT TECH2250

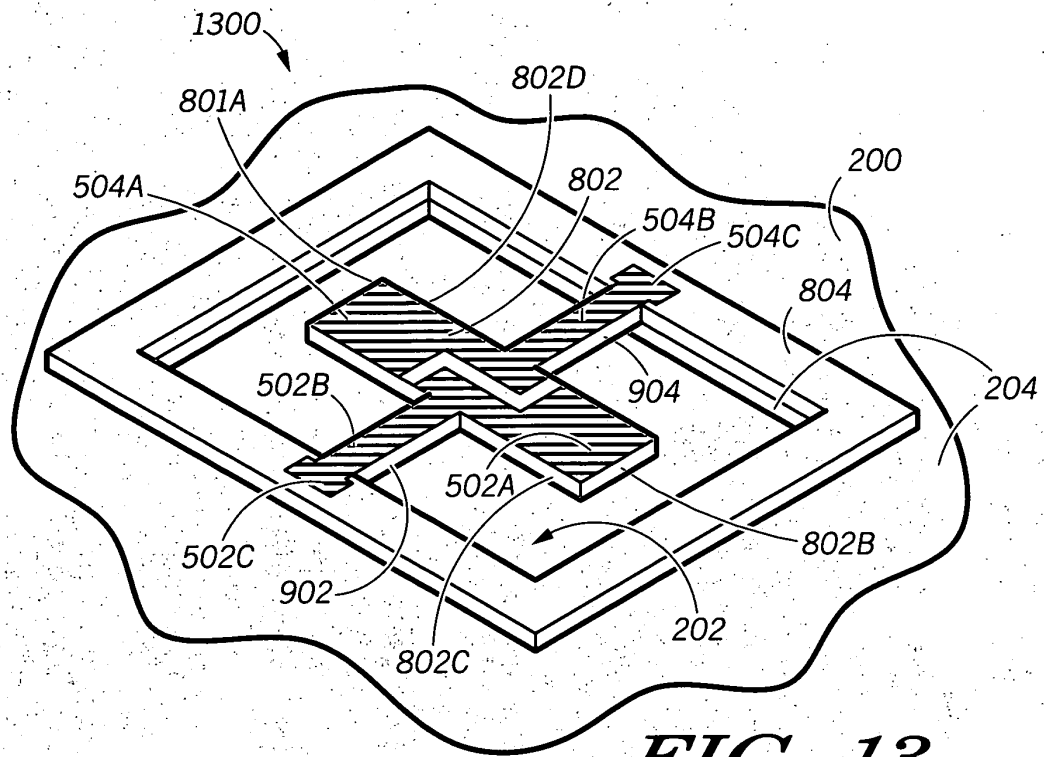


FIG. 13

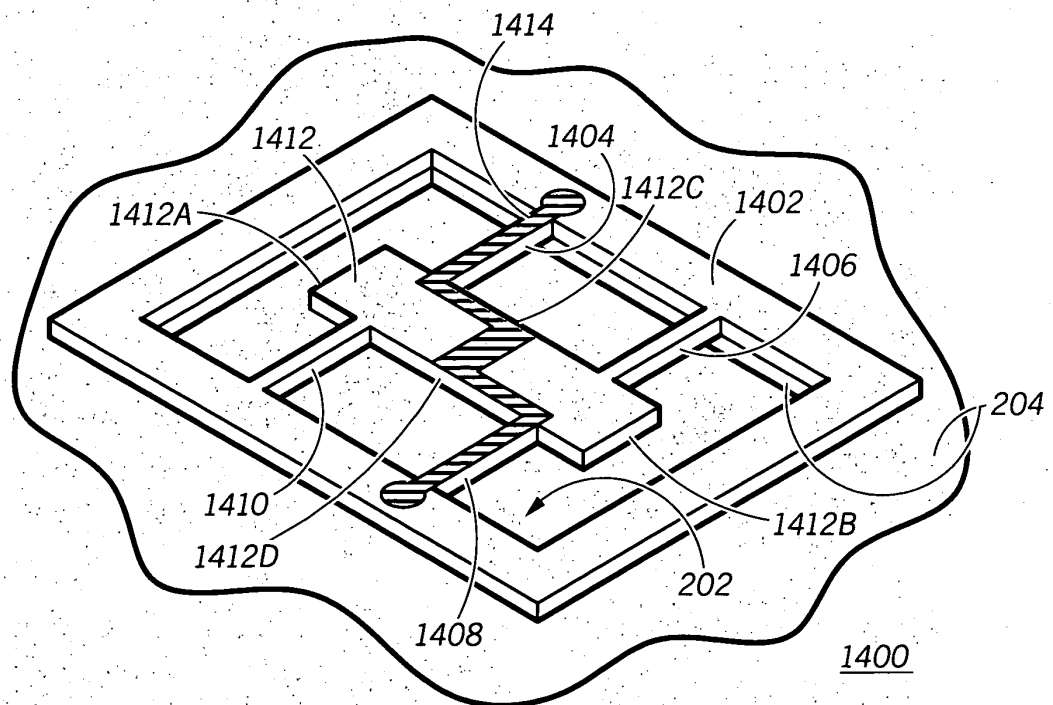


FIG. 14

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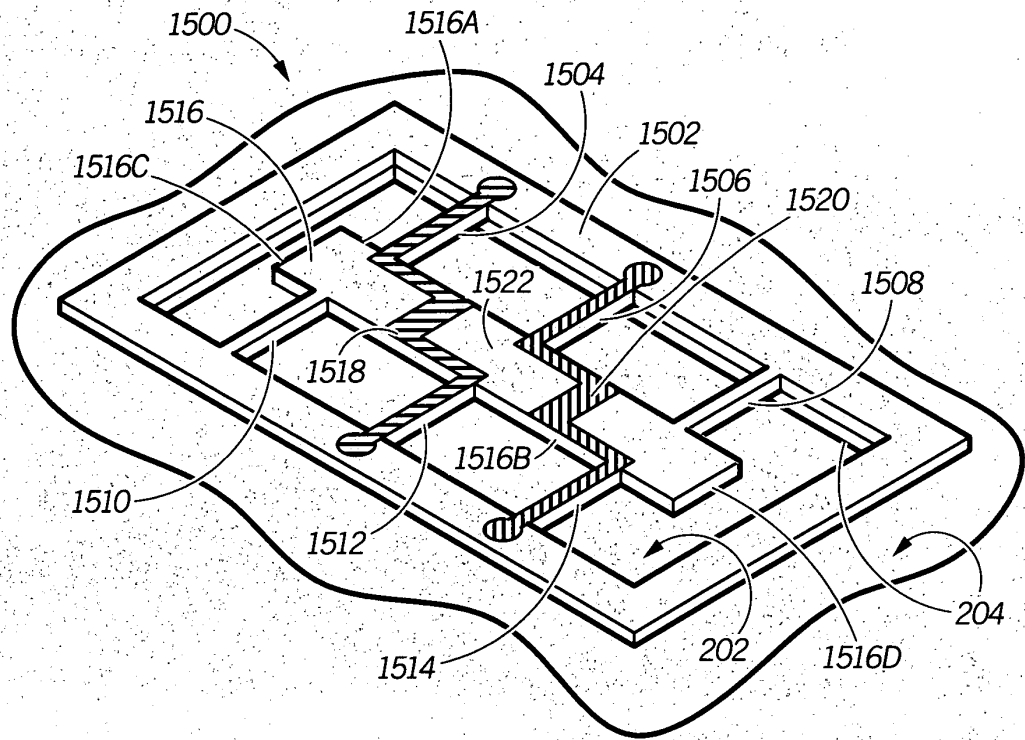


FIG. 15

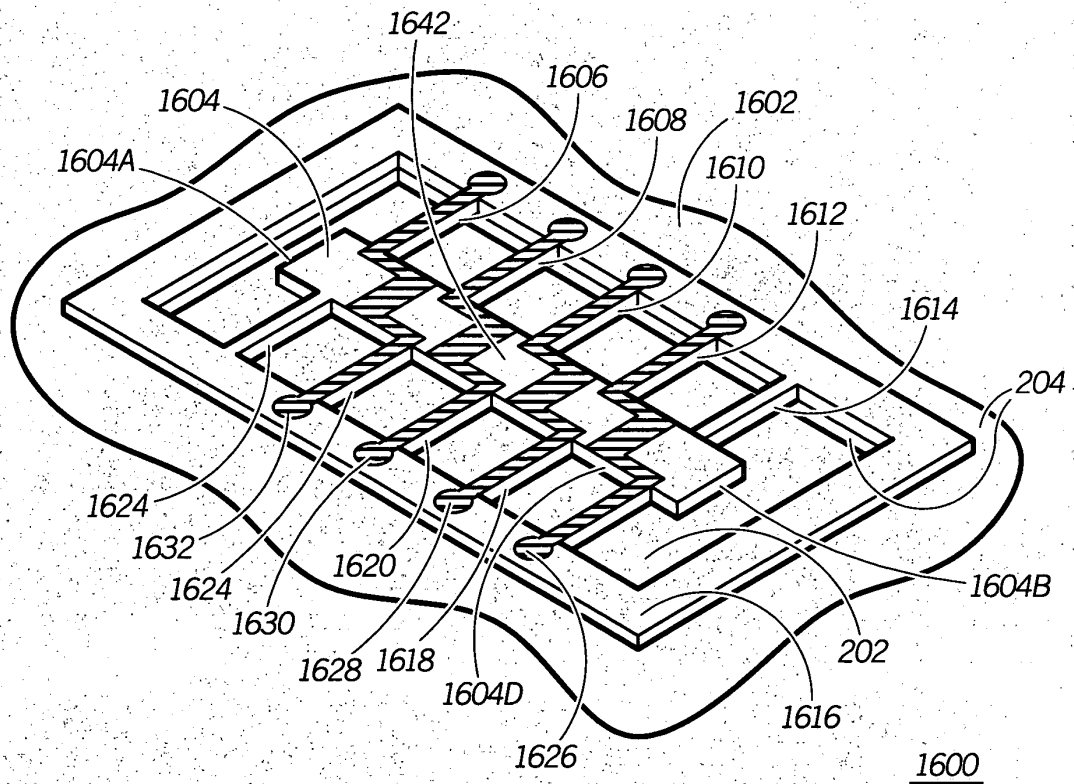


FIG. 16

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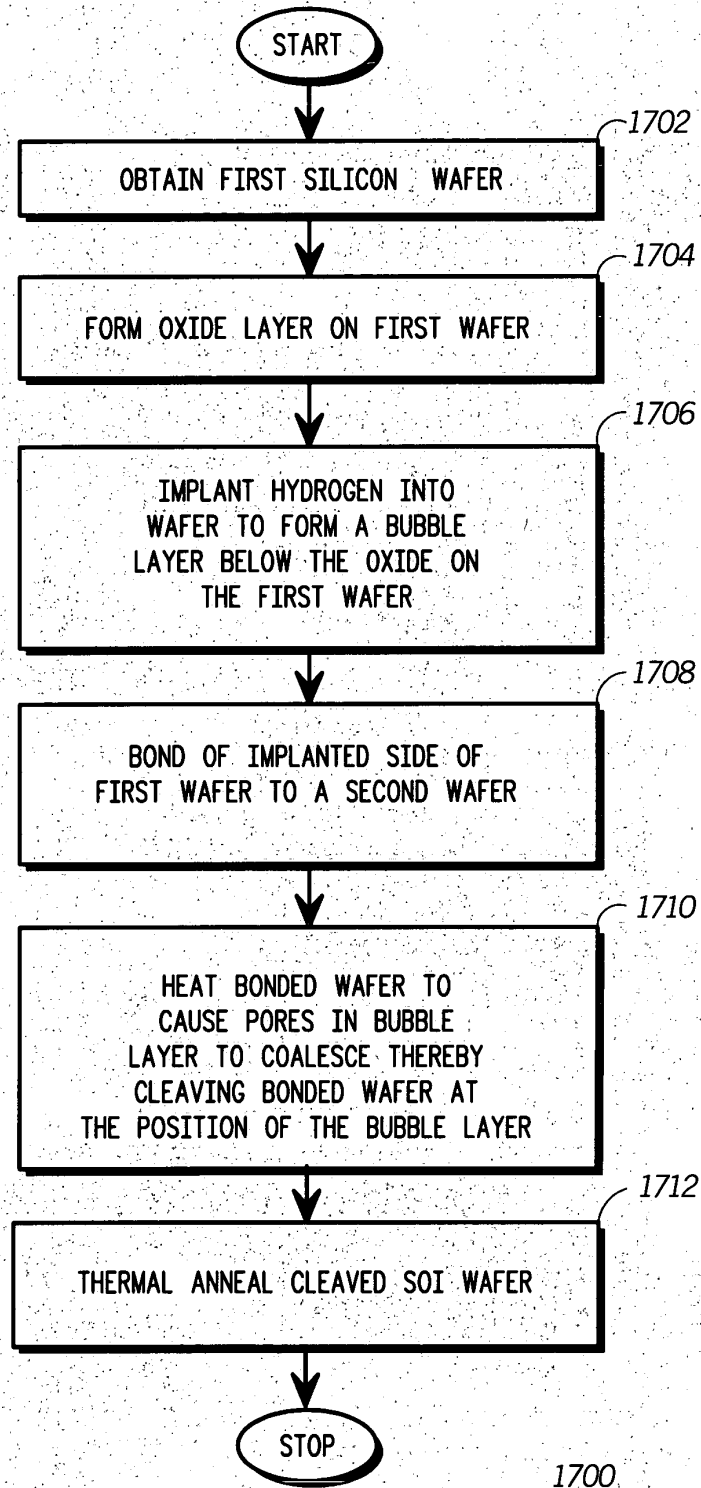


FIG. 17

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FIG. 18

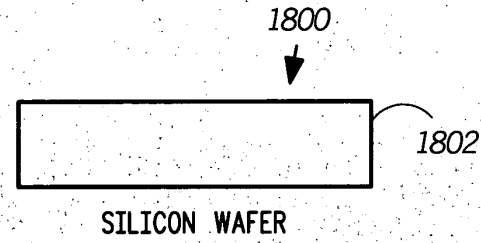


FIG. 19

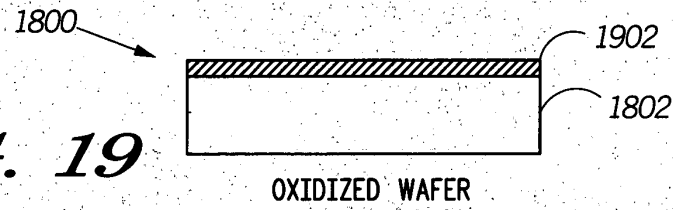


FIG. 20

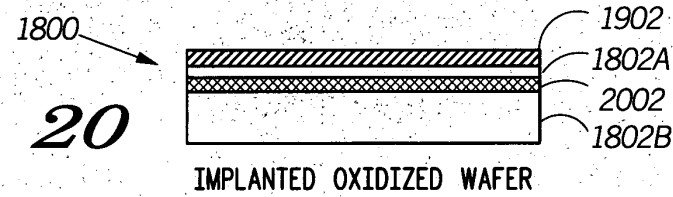


FIG. 21

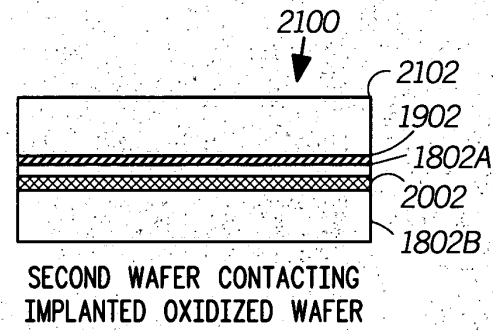
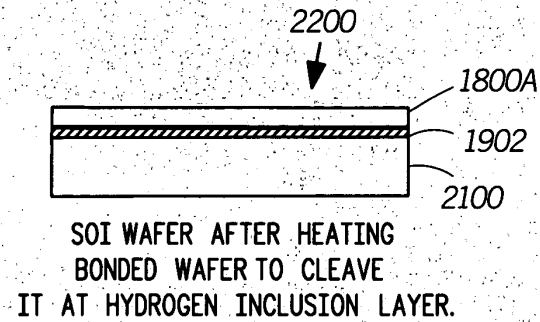


FIG. 22



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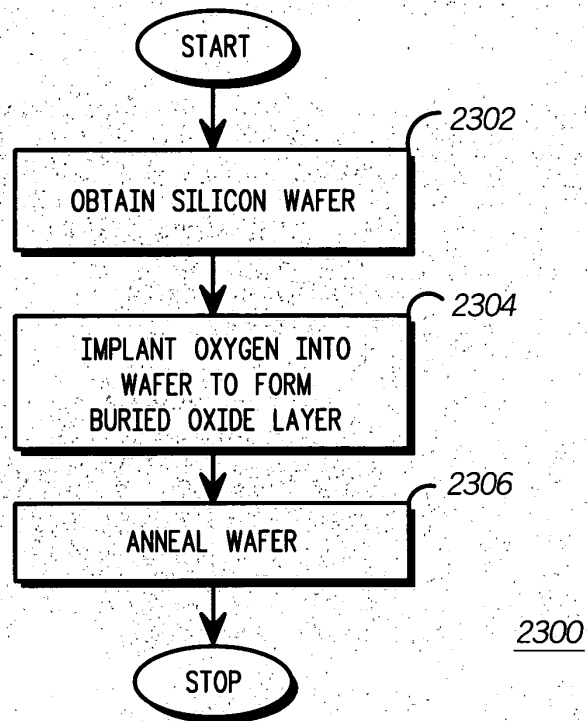


FIG. 23

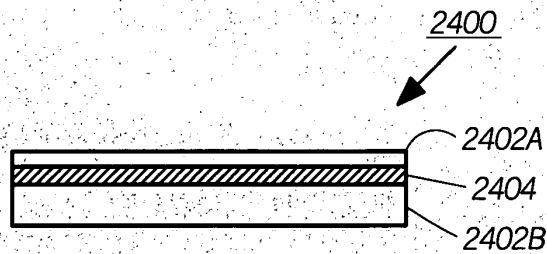


FIG. 24



FIG. 25

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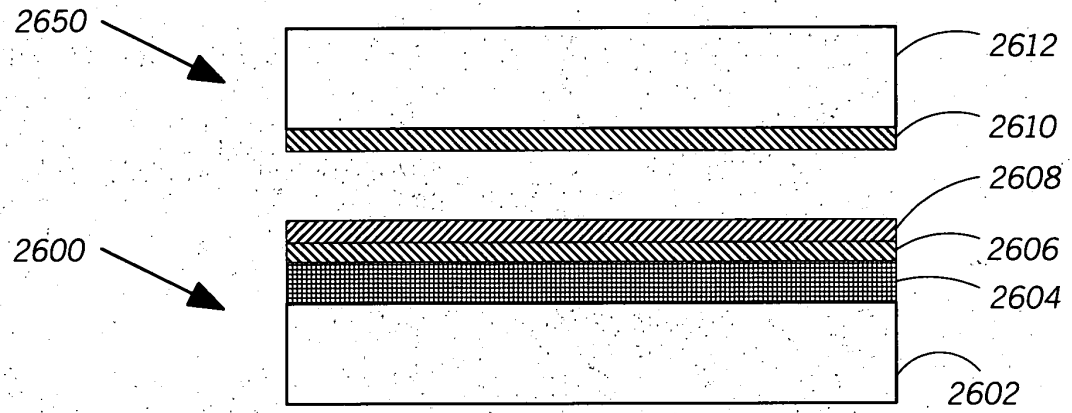


FIG. 26

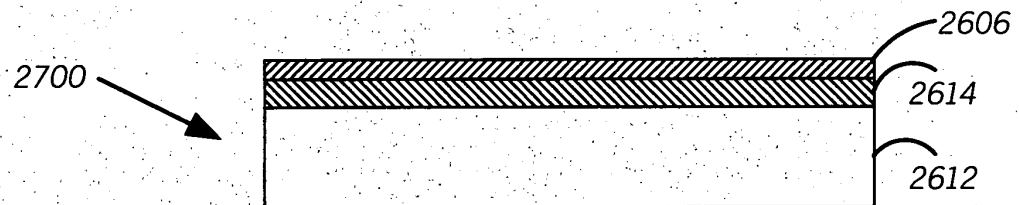


FIG. 27

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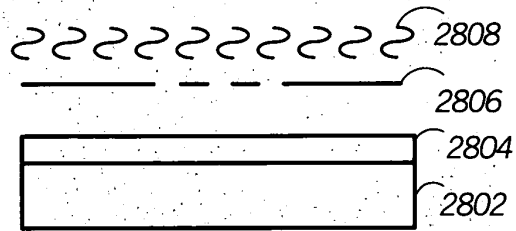


FIG. 28

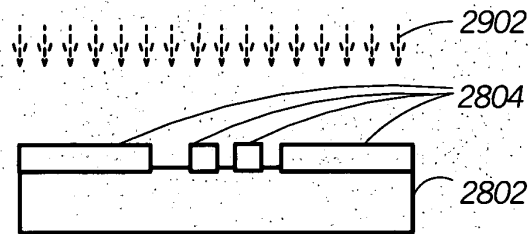


FIG. 29

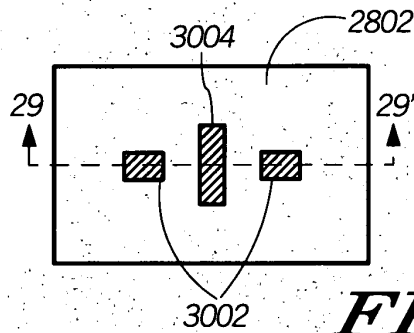


FIG. 30

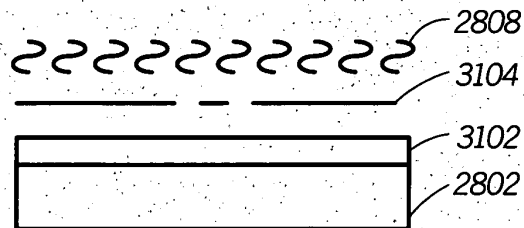


FIG. 31

FIG. 28

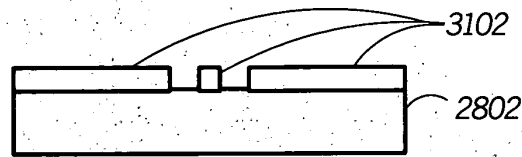


FIG. 32

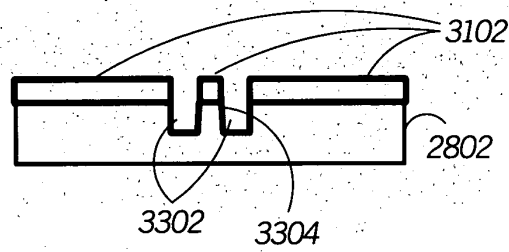


FIG. 33

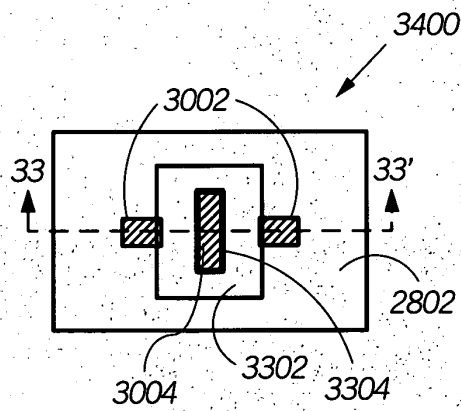


FIG. 34

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FIG. 35

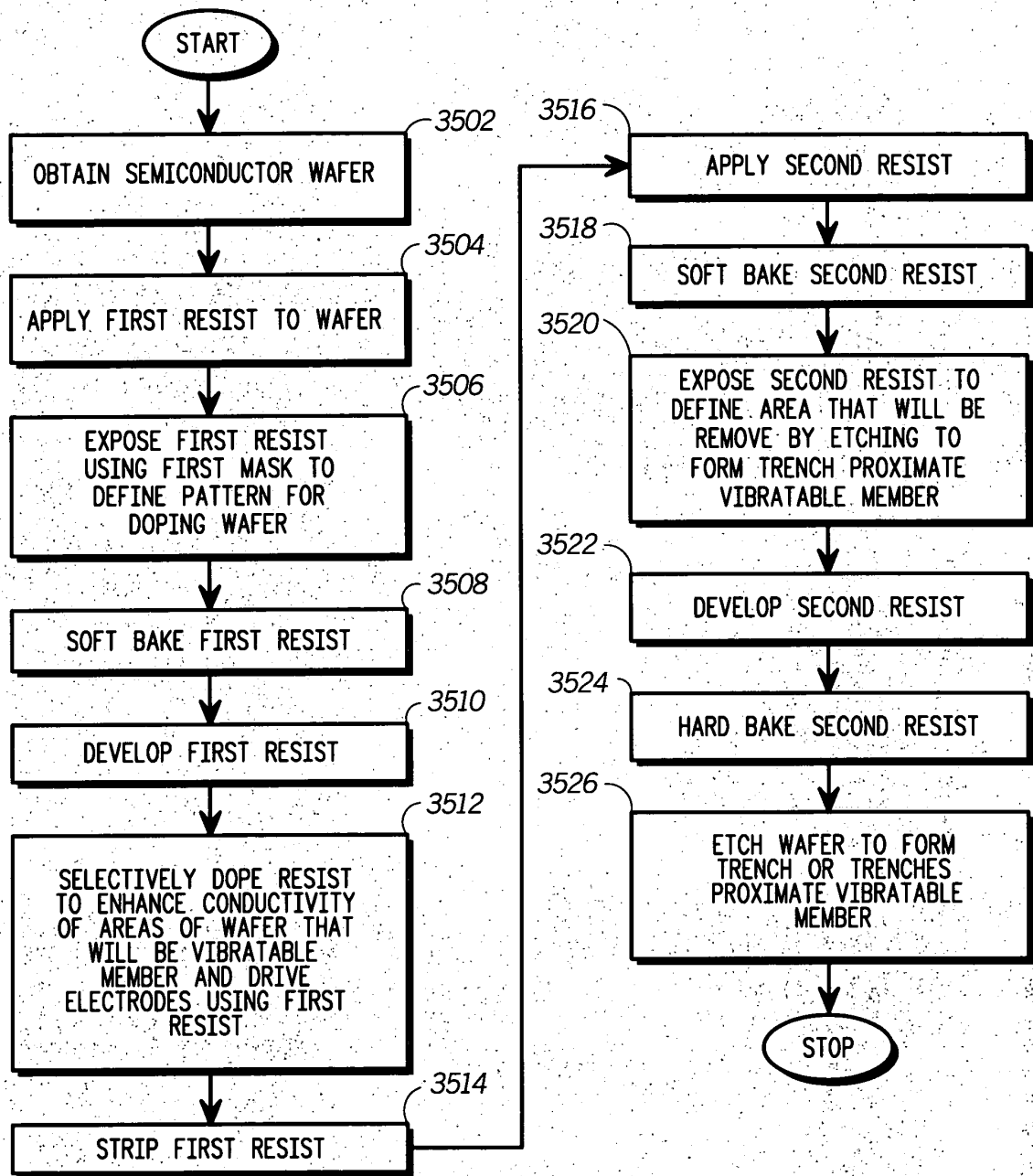


FIG. 35

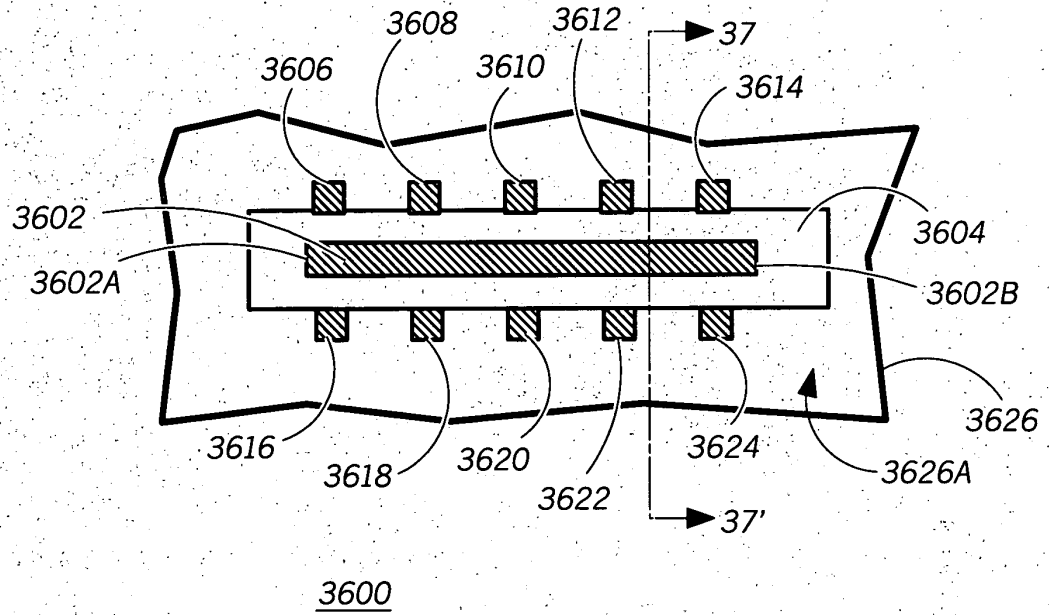


FIG. 36

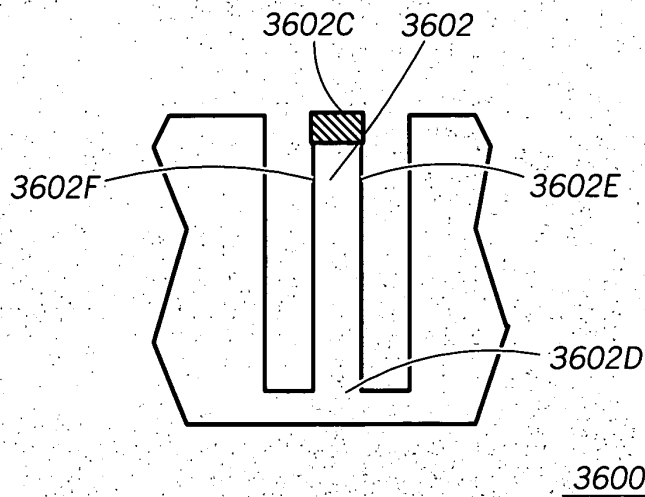


FIG. 37

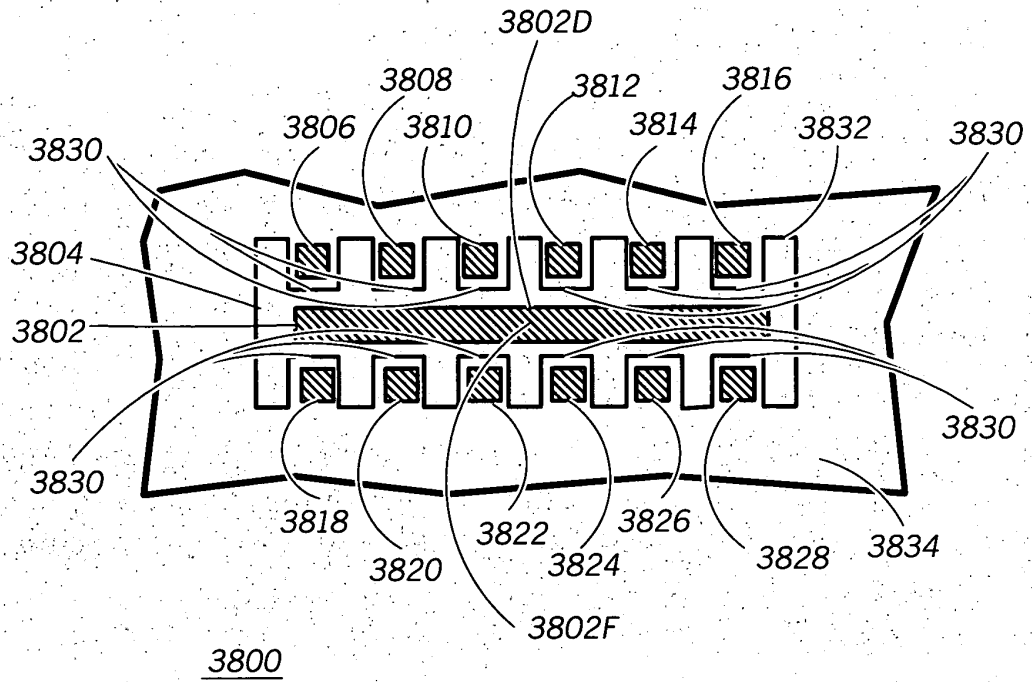


FIG. 38

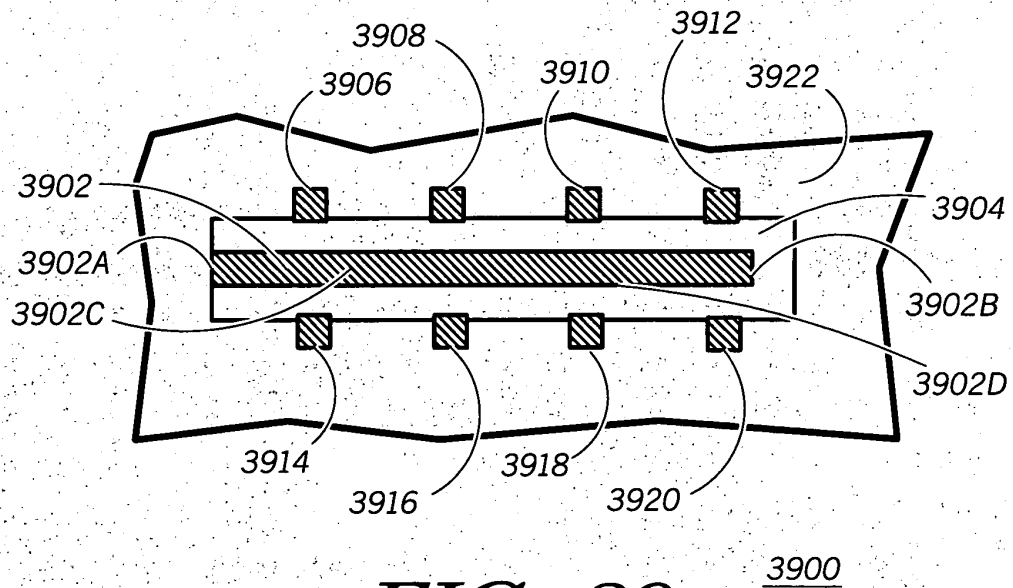


FIG. 39

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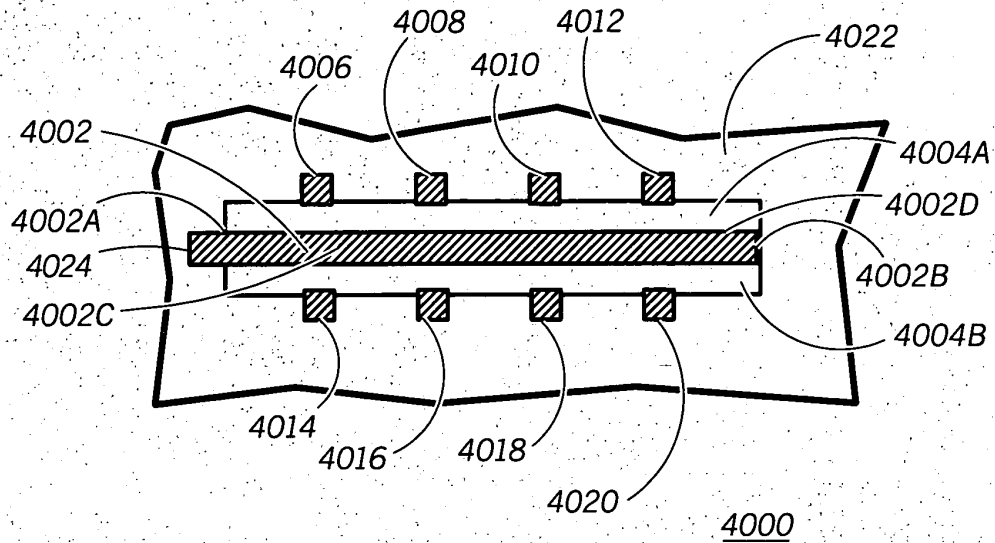


FIG. 40

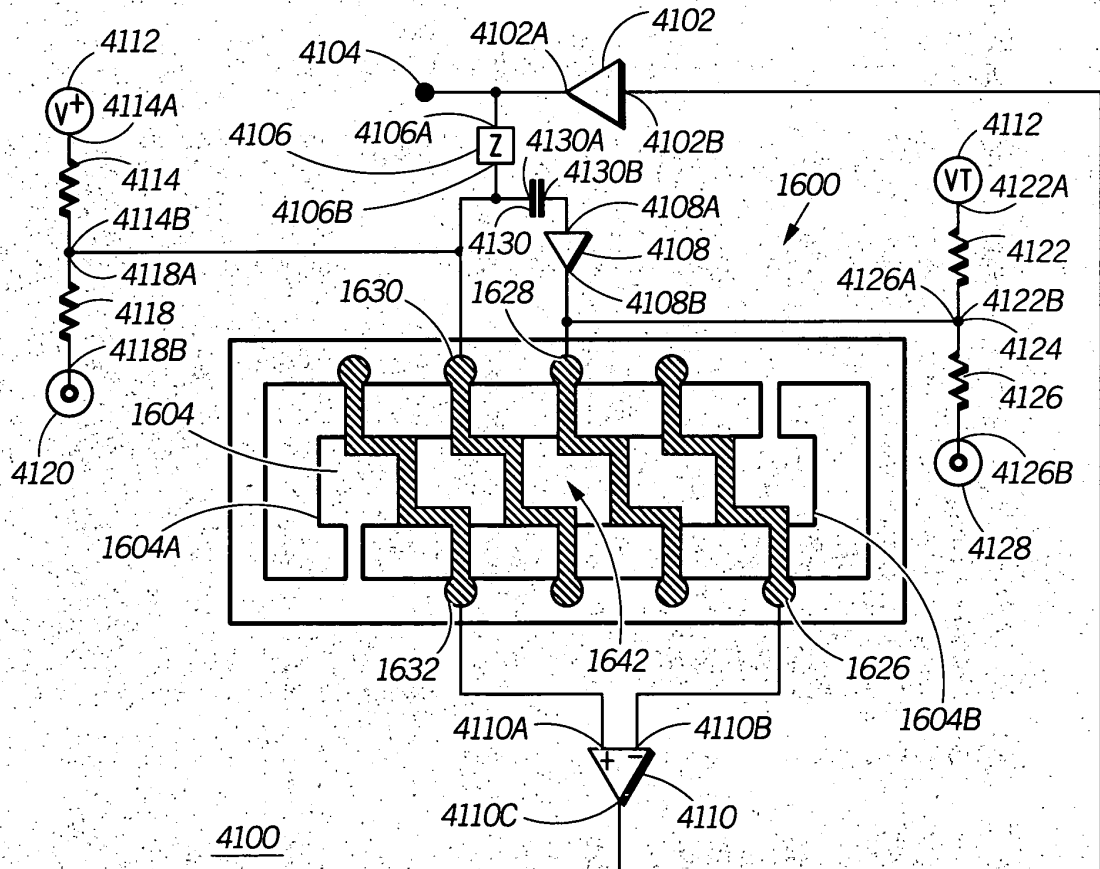


FIG. 41

TOP SECRET

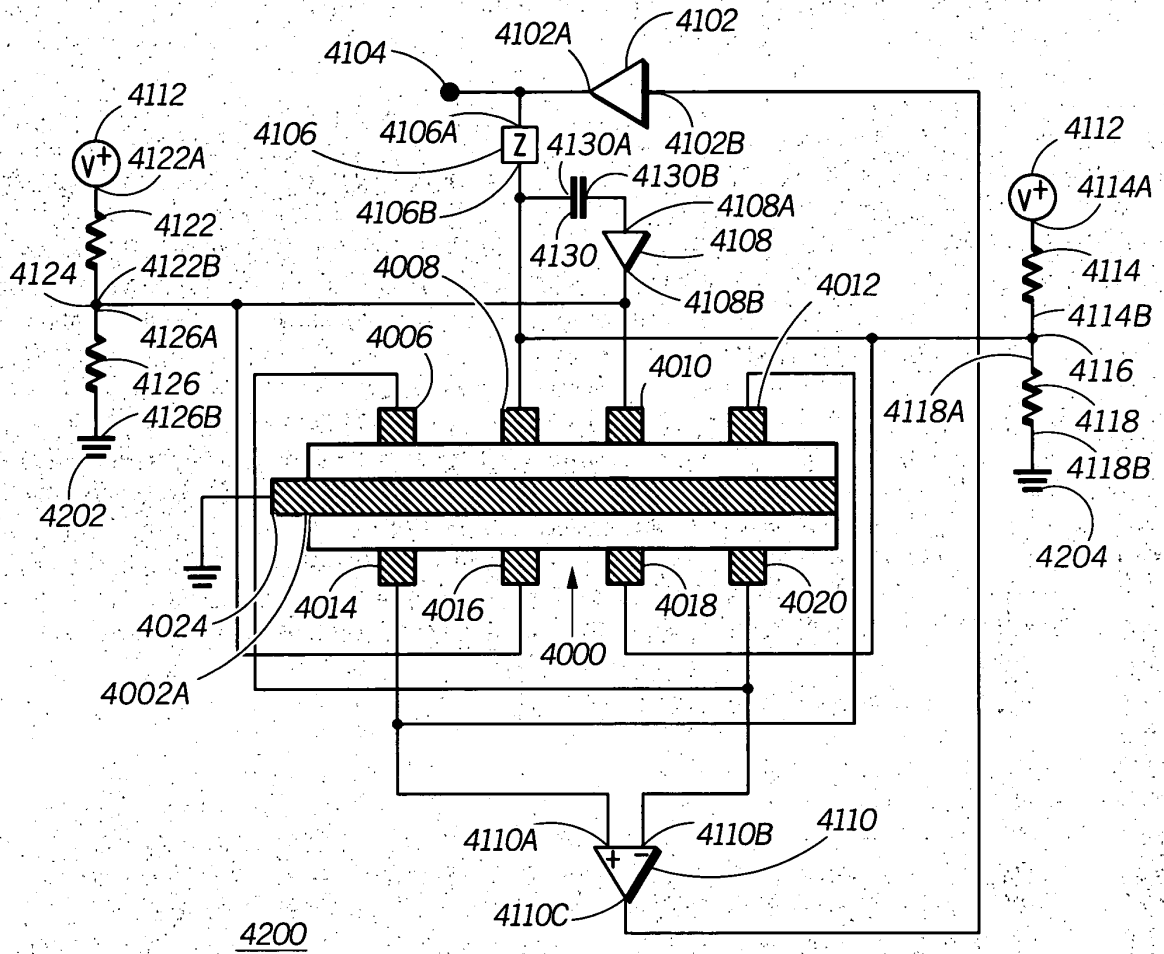


FIG. 42